

## PCIe® Gen 4 NVMe M.2 2280 SSD

The Global Leader in Specialized Storage and Memory Solutions





## **Key Features**

- Superior Read/Write performance
- MCU-based Power Loss Protection Design with Level 4 (data-in-flight) protection\*
- Self-Encrypting Drive (SED) with AES 256-bit Encryption, TCG Opal 2.0\*
- Thermal Heatsink Solutions\*\*
- End-to-End Data Path Protection
- Anti-sulfuric resistor support\*
- \* May vary by product and project support
- \*\* Customization available on a project basis.

ATP NVMe™ M.2 2280 SSDs with the PCI Express® (PCIe®) Gen 4 x4 interface meet the growing need for high-speed data transfer in today's demanding applications.

Up to 3.84 TB capacity, support for I-Temp (40°C to 85°C: N651Si) or C-Temp (0°C to 70°C: N601Sc) operation, plus AES 256-bit encryption and TCG Opal 2.0 security make these SSDs ideal for read/write-intensive mission-critical applications, such as data logging, surveillance, and imaging systems.

With twice the bandwidth of the previous generation (8 GT/s), PCle Gen 4's 16 GT/s data rate translates to a bandwidth of 2 GB/s for every PCle lane, enabling these SSDs to transfer data faster. ATP's PCle Gen 4 SSDs use x4 lanes for a maximum bandwidth of 8 GB/s.

Thermal management options for optimal heat dissipation include a nickel-coated copper heat spreader on controller and a 4 mm or 8 mm fin-type heatsink design.



A: Customization option available on a project basis.

## **Specifications**

PCIe® Gen 4 NVMe M.2 2280 SSD							
Product Line							
	N651Si	N601Sc					
Interface	PCIe G4 x4						
Flash Type	3D TLC						
Form Factor	M.2 2280-D6-M <sup>1</sup> M.2 2280-D2-M						
Operating Temperature	-40°C to 85°C	-40°C to 85°C 0°C to 70°C					
Power Loss Protection Options	Hardware + Firmware Based or Firmware Based	Firmware Based					
Optional SED Features	AES 256-bit Encryption, TCG Opal 2.0						
Capacity	240 GB to 3.84 TB						
	Performance						
Sequential Read (MB/s) up to	6	5,450					
Sequential Write (MB/s) up to	6	5,050					
Random Reads IOPS up to	1,09	94,000					
Random Writes IOPS up to	1,19	91,000					
Endurance and Reliability							
Endurance (TBW) <sup>2</sup> up to	10,760 TB						
Reliability MTBF @ 25°C	>2,000,000 hours						
	Others						
Dimensions (mm)	80.0 x 22.0 x 3.85 80.0 x 24.4 x 12.5 (with 8 mm heatsink)	80.0 x 22.0 x 3.6 80.0 x 24.4 x 12.5 (with 8 mm heatsink)					
Certifications	CE, FCC, BSMI, UKCA, RoHS, REACH						
Warranty	2 '	years					

<sup>1.</sup> M.2 2280-D6-M form factor (max height: 3.85mm), offers Hardware Based Power Loss Protection. M.2 2280-D2-M form factor (max height: 3.6mm), provides Firmware Based Power Loss Protection.

<sup>2.</sup> Under highest Sequential write value. May vary by density, configuration and applications.

Hot Items Ordering Information					
Product Line	Capacity <sub>1</sub>	Operating Temperature <sub>2</sub>	Power Loss Protection <sub>3</sub>	SED <sub>4</sub>	P/N
N601Sc	240GB	-0°C to 70°C	Firmware Based	_	AF240GSTJA-HBAXX
N601Sc	480GB	-0°C to 70°C	Firmware Based	-	AF480GSTJA-HBAXX
N601Sc	960GB	-0°C to 70°C	Firmware Based	-	AF960GSTJA-HBAXX
N601Sc	1920GB	-0°C to 70°C	Firmware Based	-	AF1T92STJA-HBAXX
N601Sc	3840GB	-0°C to 70°C	Firmware Based	-	AF3T84STJA-HBAXX
N601Sc	240GB	-0°C to 70°C	Firmware Based	√	AF240GSTJA-HBBXX
N601Sc	480GB	-0°C to 70°C	Firmware Based	√	AF480GSTJA-HBBXX
N601Sc	960GB	-0°C to 70°C	Firmware Based	√	AF960GSTJA-HBBXX
N601Sc	1920GB	-0°C to 70°C	Firmware Based	√	AF1T92STJA-HBBXX
N601Sc	3840GB	-0°C to 70°C	Firmware Based	√	AF3T84STJA-HBBXX

- 1 Amount of actual usable storage that can be utilized.
- 2 Refers to Case Temperature range during device operation, as indicated by SMART temperature attributes.
- 3 Hardware + Firmware-based power loss protection design with Level 4 (data-in-flight) protection; Firmware-based power loss protection design with Level 1 (data-at-rest) protection.
- 4 Allows data written to and read from the SSD to be constantly and automatically encrypted and decrypted. Conforms to TCG Opal 2.0 and uses AES 256-bit HW encryption.

Product spec and its related information are subject to change without advance notice. Please refer to <u>www.atpinc.com</u> for latest information

v1.0 062023

© Copyright 2023 ATP Electronics, Inc. All rights reserved.



The Global Leader in Specialized Storage and Memory Solutions

ATP TAIWAN (HQ)

ATP USA

ATP EUROPE

ATP JAPAN

ATP CHINA

TEL: +886-2-2659-6368 sales-apac@atpinc.com

TEL: +1-408-732-5000 sales@atpinc.com

TEL: +49-89-374-9999-0 sales-europe@atpinc.com TEL: +81-3-6260-0797 sales-japan@atpinc.com TEL: +86-21-5080-2220 sales@cn.atpinc.com